

STARPOWER

SEMICONDUCTOR

IGBT

GD2400SGL170A4S

Molding Type Module

1700V/2400A 1 in one-package

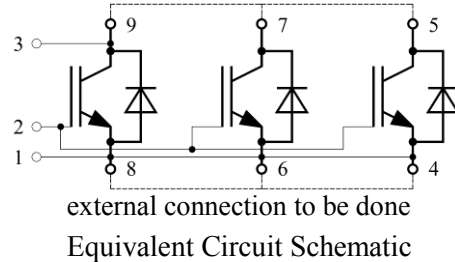
General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as high power converters.



Features

- Low $V_{CE(sat)}$ SPT+ IGBT technology
- 10 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- AlSiC baseplate for high power cycling capability
- AlN substrate for low thermal resistance



Typical Applications

- High Power Converters
- Motor Drives
- AC Inverter Drives

Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted

| Symbol | Description | GD2400SGL170A4S | Unit |
|------------|---|---|--------------------|
| V_{CES} | Collector-Emitter Voltage | 1700 | V |
| V_{GES} | Gate-Emitter Voltage | ± 20 | V |
| I_C | Collector Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=100^{\circ}\text{C}$ | 3700 2400 | A |
| I_{CM} | Pulsed Collector Current $t_p=1\text{ms}$ | 4800 | A |
| I_F | Diode Continuous Forward Current | 2400 | A |
| I_{FM} | Diode Maximum Forward Current $t_p=1\text{ms}$ | 4800 | A |
| P_D | Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$ | 15.0 | kW |
| T_{jmax} | Maximum Junction Temperature | 175 | $^{\circ}\text{C}$ |
| T_{jop} | Operating Junction Temperature | -40 to +150 | $^{\circ}\text{C}$ |
| T_{STG} | Storage Temperature Range | -40 to +125 | $^{\circ}\text{C}$ |
| V_{ISO} | Isolation Voltage RMS, $f=50\text{Hz}, t=1\text{min}$ | 4000 | V |
| M | Terminal Connection Torque, Screw M4 Terminal Connection Torque, Screw M8 Mounting Torque, Screw M6 | 1.8 to 2.1 8.0 to 10 4.25 to 5.75 | N.m |
| G | Weight of Module | 1500 | g |

Electrical Characteristics of IGBT $T_C=25^{\circ}\text{C}$ unless otherwise noted**Off Characteristics**

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------|-------------------------------------|---|------|------|------|------|
| $V_{(BR)CES}$ | Collector-Emitter Breakdown Voltage | $T_j=25^{\circ}\text{C}$ | 1700 | | | V |
| I_{CES} | Collector Cut-Off Current | $V_{CE}=V_{CES}, V_{GE}=0\text{V},$ $T_j=25^{\circ}\text{C}$ | | | 5.0 | mA |
| I_{GES} | Gate-Emitter Leakage Current | $V_{GE}=V_{GES}, V_{CE}=0\text{V},$ $T_j=25^{\circ}\text{C}$ | | | 400 | nA |

On Characteristics

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------|---|---|------|------|------|------|
| $V_{GE(th)}$ | Gate-Emitter Threshold Voltage | $I_C=96.0\text{mA}, V_{CE}=V_{GE},$ $T_j=25^{\circ}\text{C}$ | 5.4 | 6.2 | 7.4 | V |
| $V_{CE(sat)}$ | Collector to Emitter Saturation Voltage | $I_C=2400\text{A}, V_{GE}=15\text{V},$ $T_j=25^{\circ}\text{C}$ | | 2.00 | 2.45 | V |
| | | $I_C=2400\text{A}, V_{GE}=15\text{V},$ $T_j=125^{\circ}\text{C}$ | | 2.40 | | |
| | | $I_C=2400\text{A}, V_{GE}=15\text{V},$ $T_j=150^{\circ}\text{C}$ | | 2.50 | | |

Switching Characteristics

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------|--|--|------|------|------|------------|
| $t_{d(on)}$ | Turn-On Delay Time | $V_{CC}=900V, I_C=2400A,$ $R_{Gon}=0.6\Omega, R_{Goff}=0.8\Omega,$ $V_{GE}=\pm 15V, T_j=25^\circ C$ | | 415 | | ns |
| t_r | Rise Time | | | 205 | | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | | 790 | | ns |
| t_f | Fall Time | | | 200 | | ns |
| E_{on} | Turn-On Switching Loss | | | 587 | | mJ |
| E_{off} | Turn-Off Switching Loss | | | 590 | | mJ |
| $t_{d(on)}$ | Turn-On Delay Time | $V_{CC}=900V, I_C=2400A,$ $R_{Gon}=0.6\Omega, R_{Goff}=0.8\Omega,$ $V_{GE}=\pm 15V, T_j=125^\circ C$ | | 450 | | ns |
| t_r | Rise Time | | | 245 | | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | | 930 | | ns |
| t_f | Fall Time | | | 360 | | ns |
| E_{on} | Turn-On Switching Loss | | | 827 | | mJ |
| E_{off} | Turn-Off Switching Loss | | | 735 | | mJ |
| $t_{d(on)}$ | Turn-On Delay Time | $V_{CC}=900V, I_C=2400A,$ $R_{Gon}=0.6\Omega, R_{Goff}=0.8\Omega,$ $V_{GE}=\pm 15V, T_j=150^\circ C$ | | 470 | | ns |
| t_r | Rise Time | | | 260 | | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | | 935 | | ns |
| t_f | Fall Time | | | 390 | | ns |
| E_{on} | Turn-On Switching Loss | | | 863 | | mJ |
| E_{off} | Turn-Off Switching Loss | | | 776 | | mJ |
| C_{ies} | Input Capacitance | $V_{CE}=25V, f=1MHz,$ $V_{GE}=0V$ | | 162 | | nF |
| C_{res} | Reverse Transfer Capacitance | | | 5.52 | | nF |
| I_{SC} | SC Data | $t_p \leq 10\mu s, V_{GE}=15V,$ $T_j=150^\circ C, V_{CC}=1000V,$ $V_{CEM} \leq 1700V$ | | 7440 | | A |
| Q_G | Gate Charge | $V_{CC}=900V, I_C=2400A,$ $V_{GE}=-15 \dots +15V$ | | 18.5 | | μC |
| L_{CE} | Stray Inductance | | | 10 | | nH |
| $R_{CC'+EE'}$ | Module Lead Resistance, Terminal To Chip | | | 0.12 | | m Ω |

Electrical Characteristics of Diode $T_C=25^\circ\text{C}$ unless otherwise noted

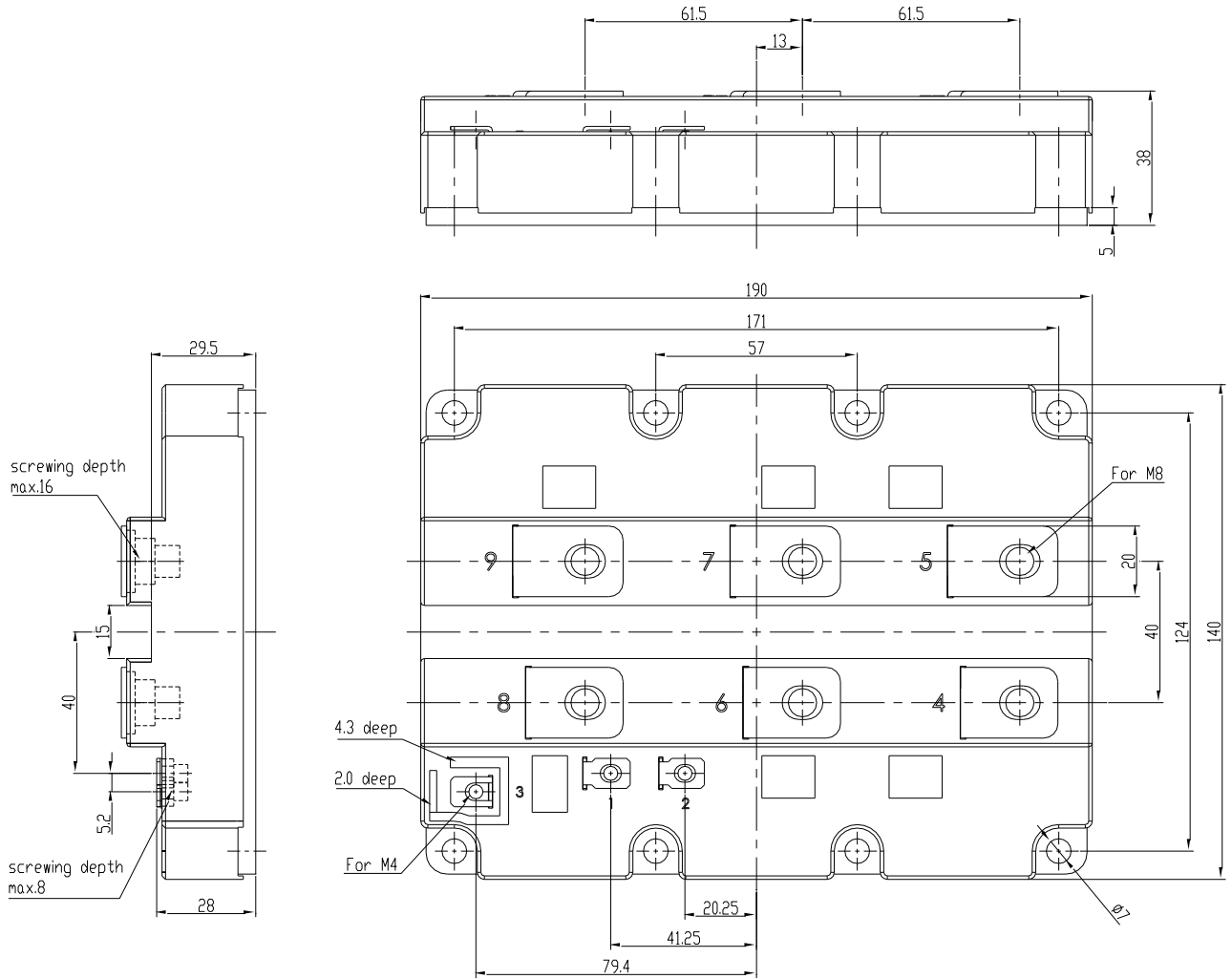
| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-----------|-------------------------------|--|------|------|------|---------------|
| V_F | Diode Forward Voltage | $I_F=2400\text{A}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$ | | 1.80 | 2.25 | V |
| | | $I_F=2400\text{A}, V_{GE}=0\text{V}, T_j=125^\circ\text{C}$ | | 1.95 | | |
| | | $I_F=2400\text{A}, V_{GE}=0\text{V}, T_j=150^\circ\text{C}$ | | 1.90 | | |
| Q_r | Recovered Charge | | | 782 | | μC |
| I_{RM} | Peak Reverse Recovery Current | $V_{CC}=900\text{V}, I_F=2400\text{A},$ $-di/dt=13500\text{A}/\mu\text{s},$ $V_{GE}=\pm 15\text{V}, T_j=25^\circ\text{C}$ | | 1790 | | A |
| E_{rec} | Reverse Recovery Energy | | | 521 | | mJ |
| Q_r | Recovered Charge | | | 1250 | | μC |
| I_{RM} | Peak Reverse Recovery Current | $V_{CC}=900\text{V}, I_F=2400\text{A},$ $-di/dt=13500\text{A}/\mu\text{s},$ $V_{GE}=\pm 15\text{V}, T_j=125^\circ\text{C}$ | | 2180 | | A |
| E_{rec} | Reverse Recovery Energy | | | 893 | | mJ |
| Q_r | Recovered Charge | | | 1410 | | μC |
| I_{RM} | Peak Reverse Recovery Current | $V_{CC}=900\text{V}, I_F=2400\text{A},$ $-di/dt=13500\text{A}/\mu\text{s},$ $V_{GE}=\pm 15\text{V}, T_j=150^\circ\text{C}$ | | 2250 | | A |
| E_{rec} | Reverse Recovery Energy | | | 1010 | | mJ |

Module Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Min. | Typ. | Max. | Unit |
|------------|-------------------------------|------|------|------|------|
| R_{thJC} | Junction-to-Case (per IGBT) | | | 9.98 | K/kW |
| | Junction-to-Case (per Diode) | | | 14.5 | |
| R_{thCH} | Case-to-Heatsink (per IGBT) | | 10.1 | | K/kW |
| | Case-to-Heatsink (per Diode) | | 14.7 | | |
| | Case-to-Heatsink (per Module) | | 6.0 | | |

Package Dimensions

Dimensions in Millimeters



Terms and Conditions of Usage

The data contained in this product datasheet is exclusively intended for technically trained staff. you and your technical departments will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to such application.

This product data sheet is describing the characteristics of this product for which a warranty is granted. Any such warranty is granted exclusively pursuant the terms and conditions of the supply agreement. There will be no guarantee of any kind for the product and its characteristics.

Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of our product, please contact the sales office, which is responsible for you (see www.powersemi.cc), For those that are specifically interested we may provide application notes.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the Product in aviation applications, in health or live endangering or life support applications, please notify.

If and to the extent necessary, please forward equivalent notices to your customers.
Changes of this product data sheet are reserved.